

### **General Description**

The WSF90N10 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSF90N10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

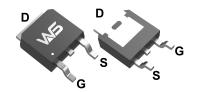
# **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
100V	6mΩ	90A

### **Applications**

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

# **TO-252 Pin Configuration**





#### **Absolute Maximum Ratings**

Symbol	Parameter Rati		Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	90	Α
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	50	Α
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	13	Α
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	10	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2,</sup> T <sub>C</sub> =25°C	300	Α
EAS	Avalanche Energy, Single pulse,L=0.5mH	180	mJ
I <sub>AS</sub>	Avalanche Current, Single pulse,L=0.5mH	27	Α
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation⁴	104	W
P <sub>D</sub> @T <sub>C</sub> =100°C	Total Power Dissipation <sup>4</sup>	42	W
T <sub>STG</sub>	Storage Temperature Range -55 to 150		℃
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		1.2	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V , $I_D$ =250uA	100			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.096		V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =15A		6	9	mΩ
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		10	15	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V V I 050-A	1.0	1.6	2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		-5.5		mV/℃
l	Drain Source Lookage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C	<sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃		1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}$ C			5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		40		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.1	1.8	Ω
Qg	Total Gate Charge (10V)			43		
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =30V , V <sub>GS</sub> =10V , I <sub>D</sub> =15A		9.5		nC
$Q_{gd}$	Gate-Drain Charge			9.0		
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}$ =50V , $V_{GS}$ =10V , $R_{G}$ =3 $\Omega$ , $I_{D}$ =1A		18		
Tr	Rise Time			11		no
$T_{d(off)}$	Turn-Off Delay Time			55		- ns
T <sub>f</sub>	Fall Time			70		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V , V <sub>GS</sub> =0V , f=1MHz		2400		
Coss	Output Capacitance			355		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			60		

### **Diode Characteristics**

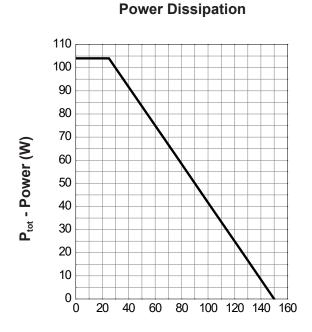
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	$V_G$ = $V_D$ = $0V$ , Force Current			40	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				160	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =15A , T <sub>J</sub> =25℃			1.3	V
t <sub>rr</sub>	Reverse Recovery Time	IF=15A,dI/dt=100A/µs,T <sub>J</sub> =25℃		48		nS
Q <sub>rr</sub>	Reverse Recovery Charge			70		nC

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec. 2. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2% 3. The EAS data shows Max. rating . The test condition is V<sub>DS</sub>=50V,V<sub>GS</sub>=10V,L=0.5mH,I<sub>AS</sub>=27A

- 5. The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

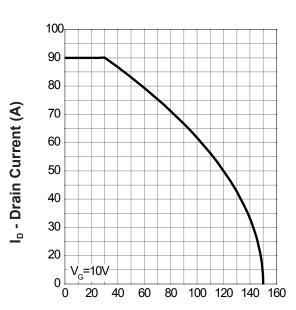


# **Typical Operating Characteristics**



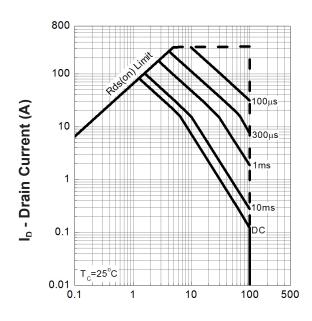
T<sub>c</sub> - Case Temperature (°C)

#### **Drain Current**



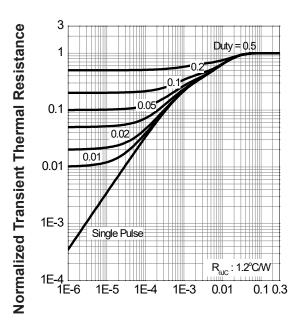
T<sub>c</sub> - Case Temperature (°C)

# **Safe Operation Area**



V<sub>DS</sub> - Drain - Source Voltage (V)

# **Thermal Transient Impedance**

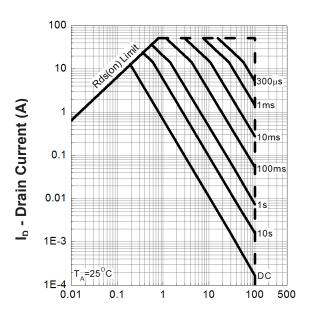


**Square Wave Pulse Duration (sec)** 



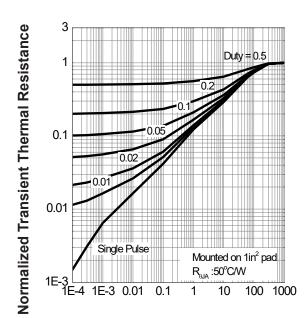
# **Typical Operating Characteristics**

#### Safe Operation Area



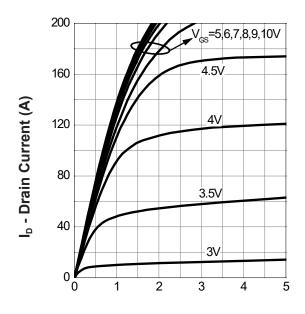
V<sub>DS</sub> - Drain - Source Voltage (V)

### **Thermal Transient Impedance**



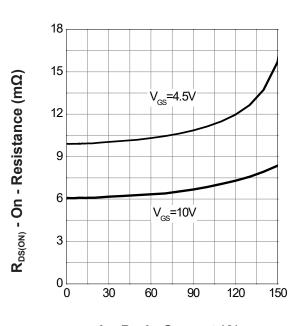
**Square Wave Pulse Duration (sec)** 

# **Output Characteristics**



V<sub>DS</sub> - Drain - Source Voltage (V)

#### **Drain-Source On Resistance**



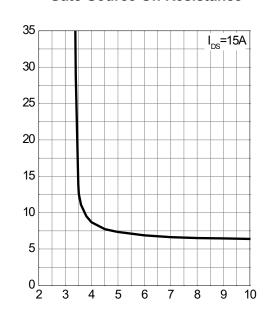
I<sub>D</sub> - Drain Current (A)



R<sub>DS(ON)</sub> - On - Resistance (mΩ)

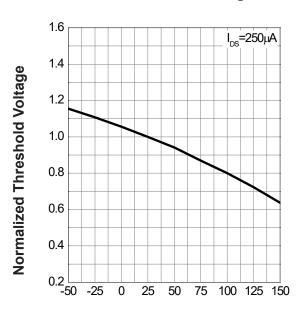
# **Typical Operating Characteristics**

# **Gate-Source On Resistance**



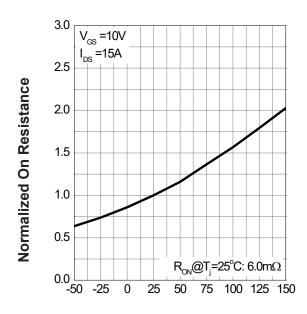
V<sub>GS</sub> - Gate - Source Voltage (V)

# **Gate Threshold Voltage**



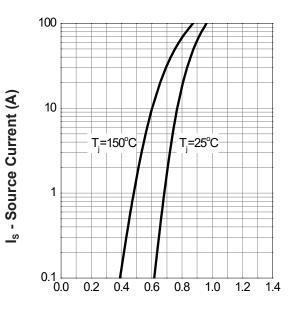
T<sub>i</sub> - Junction Temperature (°C)

# **Drain-Source On Resistance**



T<sub>j</sub> - Junction Temperature (°C)

# **Source-Drain Diode Forward**

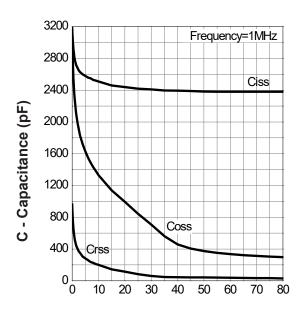


V<sub>SD</sub> - Source - Drain Voltage (V)



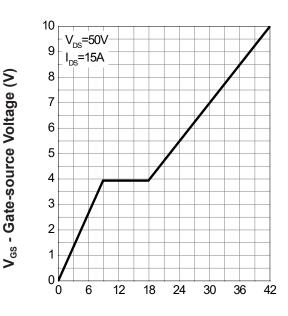
# **Typical Operating Characteristics**

# Capacitance



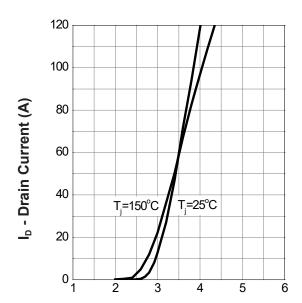
V<sub>DS</sub> - Drain-Source Voltage (V)

# **Gate Charge**



Q<sub>G</sub> - Gate Charge (nC)

### **Transfer Characteristics**



V<sub>GS</sub> - Gate-Source Voltage (V)



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